

Revision History

| Date | Rev. No. | Page | Summary |
|------------|----------|------|-------------|
| 17.01.2025 | 0 | ALL | FIRST ISSUE |
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* Description

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amo rphous silicon TFT as a switching device. This module is composed of a Transmissive type TFT-LCD Panel, driver circuit,back-light unit. The resolution of a 2.76 " TFT-LCD contains 480x480 pixels, and can display up to 16.7M colors.

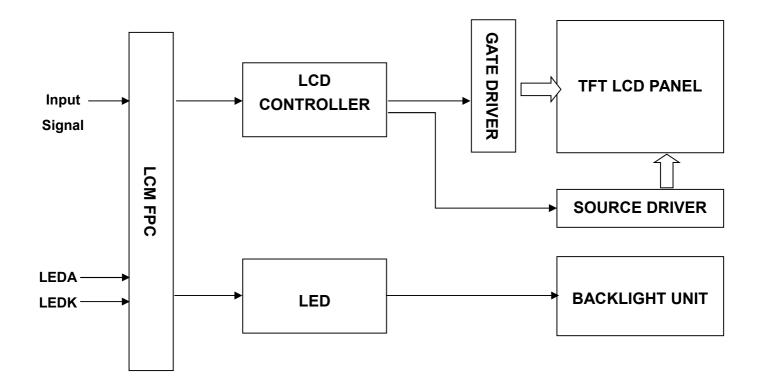
* Features

| General Information Items | Specification | l lait | Nata |
|------------------------------|------------------------------------|---------|------|
| BBV | Main Panel | – Unit | Note |
| Display Area (AA) | 70.13 x 70.13 (2.76 Inch) | mm | - |
| Driver Element | TFT Active Matrix | - | - |
| Display Colors | 16.7 Million | colors | - |
| Number of Pixels | 480 x RGB x480 | dots | - |
| Pixel Arrangement | RGB Vertical Stripe | - | - |
| Pixel Pitch | 0.1461 x 0.1461 | mm | - |
| Viewing Angle | ALL | o'clock | - |
| Controller IC | ST7701S (Sitronix) | - | - |
| LCM Interface | 2-Lane MIPI | - | - |
| Display Mode | IPS, Transmissive / Normally Black | - | - |
| Operating Temperature | -20°C ~ +70°C | °C | - |
| Storage Temperature | -30°C ~ +80°C | °C | - |

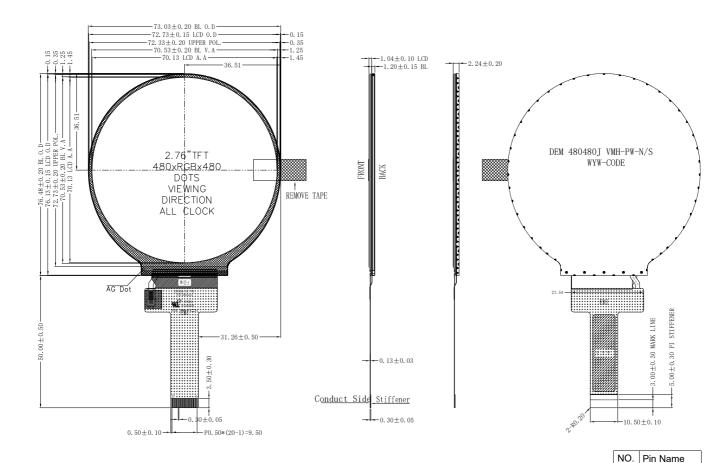
* Mechanical Information

| | ltem | Min. | Тур. | Max. | Unit | Note |
|----------------|---------------|------|-------|------|------|------|
| | Horizontal(H) | - | 73.03 | - | mm | - |
| Module Size | Vertical(V) | - | 76.48 | - | mm | - |
| SIZE | Depth(D) | - | 2.24 | - | mm | - |
| | Weight | | 21 | - | g | - |

1. Block Diagram

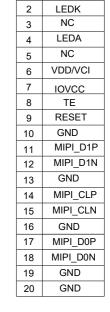


2. Outline Dimension



Note: The opening of top case must less than LCD POL 0.3mm at least, the LCD V.A is the Recommended opening of Lens.





NC

1

−0 LED− K

К

Input Terminal Pin Assignment

| NO | SYMBOL | DISCRIPTION | I/O |
|----|----------|---|-----|
| 1 | NC | | |
| 2 | LEDK | Cathode pin of backlight. | Р |
| 3 | NC | | |
| 4 | LEDA | Anode pin of backlight. | Р |
| 5 | NC | | |
| 6 | VDD/VCI | Supply Voltage (3.3V). | Р |
| 7 | IOVCC | I/O power supply voltage. | Р |
| 8 | TE | -Tearing effect output Leave the pin to open when not in use. | 0 |
| 9 | RESET | - The external reset input. Initializes the chip with a low input. Be sure to execute a power-on reset after supplying power. | I |
| 10 | GND | Ground. | Р |
| 11 | MIPI_D1P | | I/O |
| 12 | MIPI_D1N | MIPI DSI differential data pair (DSI-Dn+/-). | I/O |
| 13 | GND | Ground. | Р |
| 14 | MIPI_CLP | | I |
| 15 | MIPI_CLN | MIPI DSI differential clock pair (DSI-CLK+/-). | I |
| 16 | GND | Ground. | Р |
| 17 | MIPI_D0P | MIDI DSI differential data pair (DSI Dp. /) | I/O |
| 18 | MIPI_D0N | MIPI DSI differential data pair (DSI-Dn+/-). | I/O |
| 19 | GND | Ground. | Р |
| 20 | GND | Ground. | Р |

4. LCD Optical Characteristics

4.1 Optical Specification

| Item | | Symbol | Condition | Min. | Тур. | Max. | Unit. | Note |
|------------------|-------------------|--------------------------------|---------------|-------|-------|-------|-------|---------|
| Contrast R | atio | CR | | 1000 | 1500 | | | *(1)(2) |
| Response Time | Rising Falling | T _{R+} T _F | | | 35 | 40 | msec | *(1)(3) |
| Color Gar | nut | S(%) | | 55 | 59 | | % | * |
| | | Wx | Θ=0 | 0.237 | 0.277 | 0.317 | | CA-310 |
| | White | W _Y | Normal | 0.238 | 0.278 | 0.318 | | Test |
| | Red | Rx | Viewing Angle | 0.572 | 0.612 | 0.652 | | |
| Color Filter | | R _Y | | 0.291 | 0.331 | 0.371 | | |
| Chromacicity | Green | Gx | | 0.266 | 0.306 | 0.346 | | |
| | | G _Y | | 0.511 | 0.551 | 0.591 | | |
| | | B _X | | 0.109 | 0.149 | 0.189 | | |
| | Blue | B _Y | | 0.015 | 0.055 | 0.095 | | |
| | | ΘL | | 80 | 85 | | | *(1)(4) |
| Viewing | Hor. | ΘR | | 80 | 85 | | | |
| Angle | | ΘU | CR>10 | 80 | 85 | | | |
| | Ver. | ΘD | | 80 | 85 | | | |
| Option View D | irection | | | ŀ | ALL . | | | |

*The data comes from the LCD specification.

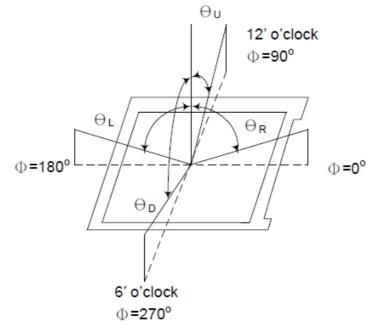
Measuring Condition

Measuring surrounding: dark room Ambient temperature: 25°C±2°C 15min. warm-up time.

Measuring Equipment

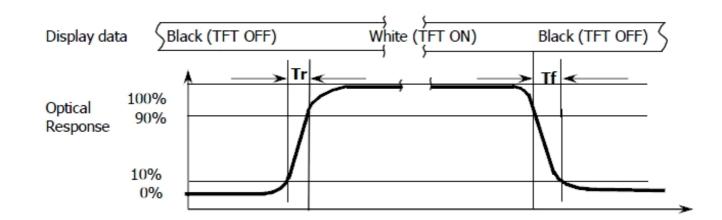
FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.

Note (1): Definition of Viewing Angle :



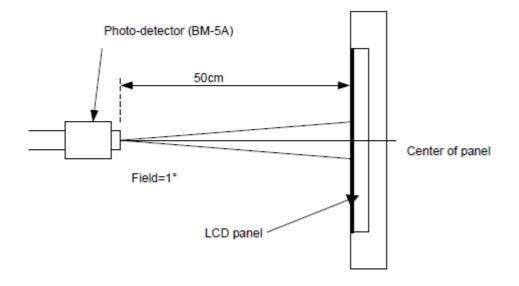
Note (2): Definition of Contrast Ratio(CR) :measured at the center point of panel

CR = Luminance with all pixels white Luminance with all pixels black



Note (3): Response Time

Note (4): Definition of optical measurement setup



5. Electrical Characteristics

5.1 Absolute Maximum Rating

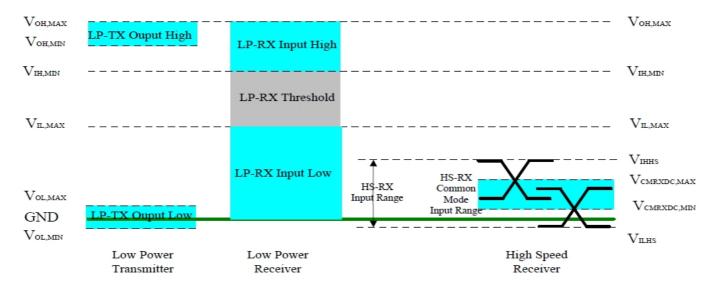
| Characteristics | Symbol | Min. | Max. | Unit | Note |
|--------------------------|-----------------|------|------|------|-------|
| Digital Supply Voltage | VCI | -0.3 | 4.6 | V | Note1 |
| Digital Interface Supply | IOVCC | -0.3 | 4.6 | V | - |
| Operating Temperature | T _{OP} | -20 | +70 | °C | - |
| Storage Temperature | Tst | -30 | +80 | °C | _ |

NOTE1: If the absolute maximum rating of even is one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.

5.2 DC Electrical Characteristics

| Characteristics | Symbol | Min. | Тур. | Max. | Unit | Note |
|--|--------|------|------|------|------|-----------------------|
| Digital Supply Voltage | VCI | 2.5 | 3.3 | 3.6 | V | - |
| Digital Interface Supply Voltage | IOVCC | 1.65 | 1.8 | 3.3 | V | - |
| Normal Mode Current Consumption | ICC | | 16 | 32 | mA | - |
| Differential Input High Threshold Voltage | VIT+ | | 0 | 50 | mV | |
| Differential Input Low Threshold Voltage | VIT- | -50 | 0 | | mV | MIPI_CLK MIPI_Data |
| Single-ended Receiver Input Operation Voltage Range | VIR | 0.5 | | 1.2 | V | |

5.3 MIPI DC Electrical Characteristics



| Parameter | Symbol | | Unit | | | | | |
|-------------------------------------|------------------|--------------|------|------|------|--|--|--|
| Farameter | Symbol | MIN | TYP | MAX | Unit | | | |
| Operation ∀oltage for MIPI Receiver | | | | | | | | |
| Low power mode operating voltage | Vlph | 1.1 | 1.2 | 1.3 | V | | | |
| MIPI Character | ristics for High | n Speed Rece | iver | • | | | | |
| Single-ended input low voltage | V ILHS | -40 | - | - | m∨ | | | |
| Single-ended input high voltage | V inns | - | - | 460 | m∨ | | | |
| Common-mode voltage | VCMRXDC | 70 | - | 330 | m∨ | | | |
| Differential input impedance | ZID | 80 | 100 | 125 | ohm | | | |
| MIPI Charac | teristics for Lo | w Power Mod | le | • | | | | |
| Pad signal voltage range | VI | -50 | - | 1350 | m∨ | | | |
| Logic 0 input threshold | VIL | 0- | - | 550 | m∨ | | | |
| Logic 1 input threshold | ∨н | 880 | - | 1350 | m∨ | | | |
| Output low level | Vol | -50 | - | 50 | m∨ | | | |
| Output high level | √он | 1.1 | 1.2 | 1.3 | V | | | |

5.4 LED Backlight Characteristics

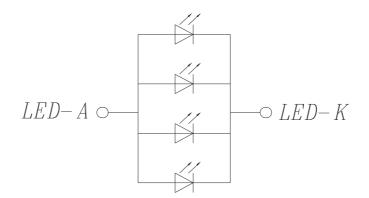
| Item | Symbol | Min. | Тур. | Max. | Unit | Note |
|-----------------|--------|-------|------|------|-------|---------|
| Forward Current | lF | | 80 | | mA | |
| Forward Voltage | VF | 5.4 | | 6.6 | V | |
| LCM Luminance | LV | 450 | 500 | | cd/m2 | Note3 |
| LED Lifetime | Hr | 50000 | | | Hour | Note1,2 |
| Uniformity | Avg | 80 | | | % | Note3 |

The backlight system is edge-lighting type with 4 chips LED

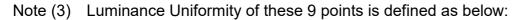
Note1: LED life time (Hr) can be defined as the time in which it continues to operate under the condition: Ta=25°C±3°C, typical IL value indicated in the above table until the brightness becomes less than 50%.

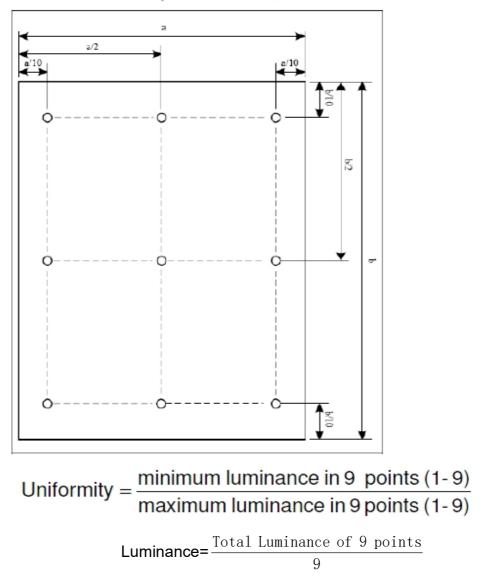
Note 2: The "LED life time" is defined as the module brightness decrease to 50% original brightness at Ta=25°C and IL=80mA. The LED lifetime could be decreased if operating IL is larger than 80mA.

The constant current driving method is suggested.



CIRCUIT DIAGRAM





6. AC Characteristics

6.1 MIPI Interface Characteristics:

6.1.1 High Speed Mode

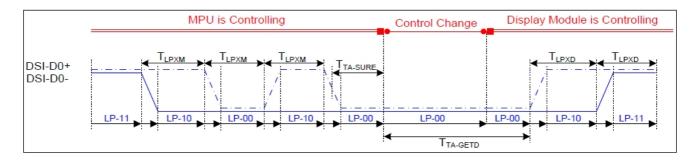


*DSI clock channel timing

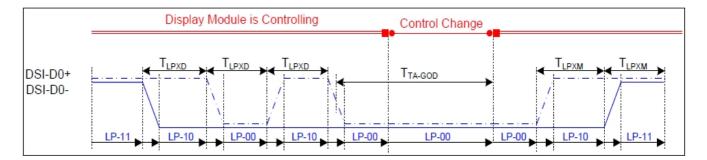
| Signal | Symbol | Parameter | MIN | MAX | Unit | Description |
|------------|--|--------------------------|------|------|------|---|
| DSI-CLK+/- | 2xUI _{INSTA} | Double UI instantaneous | 4 | 25 | ns | |
| DSI-CLK+/- | UI _{INSTA} UI _{INSTB} | UI instantaneous halfs | 2 | 12.5 | ns | UI = UI _{INSTA} = UI _{INSTB} |
| DSI-Dn+/- | tDS | Data to clock setup time | 0.15 | - | UI | |
| DSI-Dn+/- | tDH | Data to clock hold time | 0.15 | - | UI | |

* MIPI Interface-High Speed Mode Timing Characteristics

6.1.2 Low Power Mode



* Bus Turnaround (BTA) from display module to MPU Timing

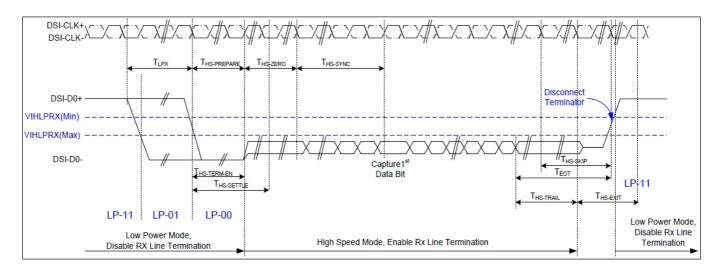


*Bus Turnaround (BTA) from MPU to display module Timing

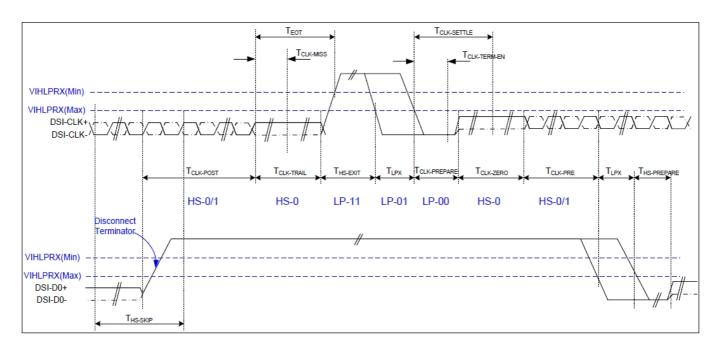
| Signal | Symbol | Parameter | Parameter MIN M | | Unit | Description | |
|-----------|-----------|---------------------------|-----------------|-------------------|------|-------------|--|
| | | Length of LP-00,LP-01, | | | | | |
| DSI-D0+/- | TLPXM | LP-10 or LP-11 periods | 50 | 75 | ns | Input | |
| | | MPU→Display Module | | | | | |
| | | Length of LP-00,LP-01, | | | | | |
| DSI-D0+/- | TLPXD | LP-10 or LP-11 periods | 50 | 75 | ns | Output | |
| | | MPU→Display Module | | | | | |
| DSI-D0+/- | TTA-SURED | Time-out before the MPU | TLPXD | 2xT _{LP} | ns | Output | |
| DSI-D0+/- | TIA-SURED | start driving | LPXD | XD | ns | Output | |
| DSI-D0+/- | | Time to drive LP-00 by | Ev.T | | | lanut | |
| DSI-D0+/- | TTA-GETD | display module | 521 | LPXD | ns | Input | |
| | | Time to drive LP-00 after | 4xTLexp | | | Output | |
| DSI-D0+/- | TTA-GOD | turnaround request-MPU | 4X1 | LPXD | ns | Output | |

*MIPI Interface Low Power Mode Timing Characteristics

6.1.3 Burst Mode



*Data lanes-Low Power Mode to/from High Speed Mode Timing



*Clock lanes- High Speed Mode to/from Low Power Mode Timing

| Signal | Symbol | Parameter | MIN | МАХ | Unit | Description |
|--|-----------------------------|---|--------------|--------------------|------|-------------|
| Low Power Mode to High Speed Mode Timing | | | | | | |
| DSI-Dn+/- | TLPX | Length of any low power state period | 50 | - | ns | Input |
| DSI-Dn+/- | THS-PREPARE | Time to drive LP-00 to prepare for HS transmission | 40+4 UI | 85+6 UI | ns | Input |
| DSI-Dn+/- | THS-TERM-EN | Time to enable data receiver line termination measured from when Dn crosses VILMAX | - | 35+4 UI | ns | Input |
| DSI-Dn+/- | THS-PREPARE + THS-ZERO | THS-PREPARE + time to drive HS-0 before the sync sequence | 140+ 10UI | - | ns | Input |
| | H | High Speed Mode to Low Power Mo | ode Timir | ng | | |
| DSI-Dn+/- | THS-SKIP | Time-out at display module to ignore transition period of EoT | 40 | 55+4 UI | ns | Input |
| DSI-Dn+/- | THS-EXIT | Time to drive LP-11 after HS burst | 100 | - | ns | Input |
| DSI-Dn+/- | THS-TRAIL | Time to drive flipped differential state after last payload data bit of a HS transmission burst | 60+4 UI | - | ns | Input |
| | Hig | h Speed Mode to/from Low Power | Mode Ti | ming | | |
| DSI-CLK+/- | TCLK-POS | Time that the MPU shall continue sending HS clock after the last associated data lane has transition to LP mode | 60+5 2UI | - | ns | Input |
| DSI-CLK+/- | TCLK-TRAIL | Time to drive HS differential state after last payload clock bit of a HS transmission burst | 60 | - | ns | Input |
| DSI-CLK+/- | THS-EXIT | Time to drive LP-11 after HS burst | 100 | - | ns | Input |
| DSI-CLK+/- | TCLK-PREPARE | Time to drive LP-00 to prepare for HS transmission | 38 | 95 | ns | Input |
| DSI-CLK+/- | TCLK-TERM-EN | Time-out at clock lan display module to enable HS transmission | - | 38 | ns | Input |
| DSI-CLK+/- | TCLK-PREPARE + TCLK-ZERO | Minimum lead HS-0 drive period before starting clock | 300 | - | ns | Input |
| DSI-CLK+/- | TCLK-PRE | Time that the HS clock shall be driven prior to any associated data lane beginning the transition from LP to HS mode | 8UI | - | ns | Input |
| DSI-CLK+/- | TEOT | Time form start of TCLK-TRAIL period to start of LP-11 state | - | 105n s+12 UI | ns | Input |

6.2 Reset Timing

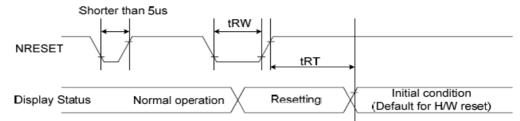


Figure 102 Reset Timing

Table 41 Reset Timing

| Signal | Symbol | Parameter | Min | Max | Unit |
|--------|--------------|----------------------|-----|------------------|------|
| | tRW | Reset pulse duration | 10 | | us |
| RESX | tRT Reset of | Boost concol | | 5(note 1,5) | ms |
| | IKI | Reset cancel | | 120 (note 1,6,7) | ms |

Note:

- The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from OTP to registers. This loading is done every time when there is H/W reset cancel time (tRT) within 5 ms after a rising edge of RESX.
- Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the Table 43.

Table 42 Reset Descript

| RESX Pulse | Action |
|---------------------|----------------|
| Shorter than 5us | Reset Rejected |
| Longer than 9us | Reset |
| Between 5us and 9us | Reset starts |

- 3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out mode. The display remains the blank state in Sleep In mode.) and then return to Default condition for Hardware Reset.
- 4. Spike Rejection also applies during a valid reset pulse as shown below:

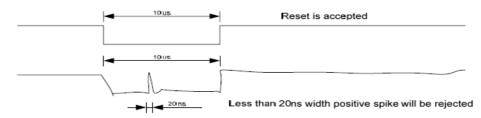


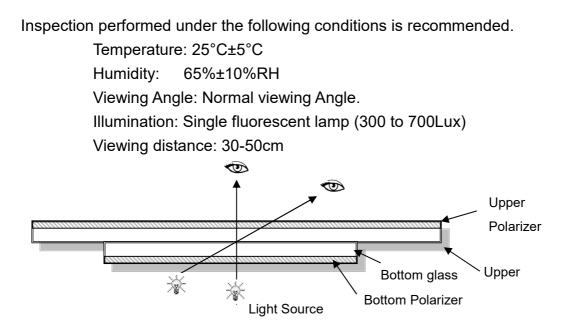
Figure 103 Positive Noise Pulse during Reset Low

- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.
- It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

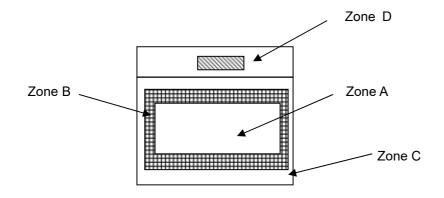
7. LCD Module Out-Going Quality Level

7.1 VISUAL & FUNCTION INSPECTION STANDARD

7.1.1 Inspection Conditions



7.1.2 Definition



Zone A : Effective Viewing Area(Character or Digit can be seen)

Zone B : Viewing Area except Zone A

Zone C : Outside (Zone A+Zone B) which can not be seen after assembly by customer

Zone D : IC Bonding Area

Note: As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer

7.1.3 Sampling Plan

According to GB/T 2828-2012, normal inspection, Class II AQL:

| Major Defect | Minor Defect |
|--------------|--------------|
| 0.65 | 1.5 |

LCD: Liquid Crystal Display, LCM: Liquid Crystal Module,

| No | Items to be inspected | Criteria | Classification of defects |
|----|-----------------------|--|---------------------------|
| | | 1) No display, Open or miss line | |
| 1 | Functional defects | 2) Display abnormally, Short | |
| | | 3) Backlight no lighting, abnormal lighting. | |
| | | etc | Major |
| 2 | Missing | Missing components and etc | , |
| | | Overall outline dimension beyond the | |
| 3 | Outline dimension | drawing is not allowed, deformation etc | |
| 4 | Color tone | Color unevenness, refer to limited sample | |
| | | Light dot,Dim spot,(Note1) | |
| 5 | Spot/Line defect | Polarizer Air Bubble, | |
| | | Polarizer accidented spot etc. | Minor |
| 6 | Soldering appearance | Good soldering , Peeling off is not allowed | |
| 0 | Soldering appearance | etc. | |
| 7 | LCD/Polarizer | Black/White spot/line, scratch, crack, etc. | |

- Note: a) Light dot: Dots appear bright and unchanged in size in which LCD panel is displaying under black pattern.
 - b) Dim dot: Dots appear dark and unchanged in size in which LCD panel is displaying under pure red, green, blue picture.

7.1.4 Criteria (Visual)

| Number | Items | Criteria(mm) | | | | |
|---|-------------------------------|--|--|--|--|--|
| 1.0 LCD Crack/Broken NOTE: X: Length Y: Width Z: Height L: Length of ITO, | (1) The edge of LCD broken | | | | | |
| | | X Y Z | | | | |
| T: Height of LCD | | ≤3.0mm <pre><inner border="" line="" of<br="">the seal</inner></pre> | | | | |
| | (2)LCD corner broken | XYZ ≤ 3.0 mm $\leq L$ $\leq T$ | | | | |
| | (3) LCD crack | Crack Not allowed | | | | |

Product Specification

| | Spot defect | ⊕ light dot (black | x/white spot , pinhole, stain,etc.) | | | | |
|-----|--------------------|------------------------------|-------------------------------------|----------------|----------|--|--------|
| | | Zone | Acce | Acceptable Qty | | | |
| | ↓ Y | Size (mm) | А | В | С | | |
| 2.0 | | Ф≤0.15 | Ignore | | | | |
| 2.0 | X | 0.15<Φ≤0.25 | 3(distance≧6mm) | | Ignore | | |
| | Φ=(X+Y)/2 | 0.25<Φ≤0.4 | 2(distance≧6mm) | | Ignore | | |
| | $\Psi = (X + 1)/2$ | Φ>0.4 | 0 | | | | |
| | | ② Dim spot (light le | eakage、dent、dark: | spot, etc) | | | |
| | | Zone | Acce | ptable Qty | | | |
| | | Size (mm) | A | В | С | | |
| | | Φ≤0.15 | Ignore | | L | | |
| | | 0.15<Φ≤0.25 | | | Ignore | | |
| | | 0.25<Φ≤0.4 | 2(distance ≥ 6 mm) |) | 5 | | |
| | | Φ>0.4 ③ Polarizer accider | 0 Ned spot | | | | |
| | | | | ptable Qty | | | |
| | | Zone | A | B | С | | |
| | | Size (mm) | | D | C | | |
| | | Φ≤0.2 | Ignore | | | | |
| | | 0.2<Φ≤0.5 | 2(distance≧ | o mm) | Ignore | | |
| | | Φ>0.5 | 0 | | | | |
| | | ④Polarizer Bubble | | | | | |
| | | Zone | Acce | eptable Qty | | | |
| | | Size (mm) | A | В | С | | |
| | | Φ≤0.2 | Ignore | | | | |
| | | 0.2<Ф≤0.4 | 3(distance≧6mm) | | | | Ignore |
| | | Φ>0.4 | 0 | | | | |
| | | | | | | | |

| 3.0 | LCD Pixel defect | Pixel bad poi | nts | | | |
|-----|------------------|--|--|----------------|--|--|
| | | Item | Zone A | Acceptable Qty | | |
| | | | Random | N≤2 | | |
| | | Bright dot | 2 dots adjacent | N≤0 | | |
| | | | 3 dots adjacent | N≤0 | | |
| | | | Random | N≤2 | | |
| | | Dark dot | 2 dots adjacent | N≤0 | | |
| | | | 3 dots adjacent | N≤0 | | |
| | | Distance | Minimum Distance Between Bright dots. Minimum Distance Between dark dots Minimum Distance Between dark and bright dot. | 5mm | | |
| | | Total bright a | Total bright and dark dot N≤4 | | | |
| | | Note: | | | | |
| | | A) Bright dot: Dots appear bright and unchanged in size in which | | | | |
| | | LCD panel is displaying under black pattern. | | | | |
| | | B) Dark dot: Dots appear dark and unchanged in size in which LCD | | | | |
| | | panel is displaying under pure red, green, blue picture. | | | | |
| | | C) 2 dot adja Picture: | icent = 1 pair = 2 dots | | | |
| | | | | | | |
| | | 2 dot adjacent 2 dot adjacen | | | | |
| | | | | | | |
| | | 2 dot adjacer | nt (vertical) 2 dot adjacent (| slant) | | |

| | Line defect (LCD | | | | | | | |
|---|----------------------|---|------------------------------|------------------|---|---------------|--|--|
| | /Polarizer backlight | Midth(mm) | Length(m | n Acceptable Qty | | ty | | |
| | black/white line, | Width(mm) | m) | А | В | С | | |
| | scratch, stain) | Ф≤0.03 | Ignore | Ignore | | | | |
| 4.0 | | 0.03 <w≤0.04< td=""><td>L≤3.0</td><td>N≤2</td><td></td><td colspan="2">Ignore</td></w≤0.04<> | L≤3.0 | N≤2 | | Ignore | | |
| | W: width, L : length | 0.04 <w≤0.05< td=""><td>L≤2.0</td><td>N≤1</td><td></td><td></td></w≤0.05<> | L≤2.0 | N≤1 | | | | |
| | N : Count | W>0.05 | W>0.05 Define as spot defect | | | | | |
| | Electronic Compo | Not allow missing par smatch, The positive | | | | lder joint,mi | | |
| 5.0 | nents SMT. | F | | | | | | |
| Display color& B 1. Color: Measuring the color coordinates, The measure rd according to the datasheet or samples. | | | | ement standa | | | | |
| 6.0 | rightness. | 2. Brightness: Measuring the brightness of White screen, The meas urement standard according to the datasheet or Samples. | | | | | | |
| LCD Mura/Wavin Not visible through 5% ND filter in 50% gray or judge to e if necessary. | | | | oy limit sampl | | | | |
| 7.0 | g/ | - | | | | | | |
| | Hot spot | | | | | | | |

Criteria (functional items)

| Number | Items | Criteria (mm) |
|--------|-----------------------|---------------|
| 1 | No display | Not allowed |
| 2 | Missing segment | Not allowed |
| 3 | Short | Not allowed |
| 4 | Backlight no lighting | Not allowed |
| | | |

8. Reliability Test Result

| Item | Condition | Inspection after test |
|----------------------------|--|----------------------------|
| High Temperature Operating | +70°C,96h | |
| Low Temperature Operating | -20°C, 96h | |
| High Temperature Storage | +80°C, 96h | Inspection after 2~4hours |
| Low Temperature Storage | -30°C, 96h | storage at room |
| High Temperature & High | +60°C, 90% RH ,96h. | temperature, the sample |
| Humidity Operating | +00 C, 90 % RT ,901. | shall be free from |
| Thermal Shock | -10°C,30 min ↔ +60°C, 30 min, | defects: |
| (Non-operation) | Change time: 5min 20CYC. | 1. Air bubble in the LCD; |
| | | 2. Non-display; |
| | C=150pF, R=330, 5points/panel | 3. Missing segments/line; |
| ESD test | Air:±8kV, 5times; Contact:±6kV, 5 times; | 4. Glass crack; |
| | (Environment: 15°C~35°C, 30%~60%). | 5. Current IDD is twice |
| | Frequency range: 10~55Hz, Stroke:1.5mm | higher than initial value. |
| Vibration (Non-operation) | Sweep:10Hz~55Hz~10Hz 2 hours for each direction | 5 |
| | of X.Y.Z. (6 hours for total) (Package condition). | |
| Box Drop Test | 1 Corner 3 Edges 6 faces, 80cm(MEDIUM BOX) | |

Remark:

- 1. The test samples should be applied to only one test item.
- 2. Sample size for each test item is 5~10pcs.
- 3. For Damp Proof Test, Pure water (Resistance > $10M\Omega$) should be used.
- 4. In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.
- 5. Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.
- 6. The color fading mura of polarizing filter should not care.

9. Cautions and Handling Precautions

9.1 Handling and Operating the Module

- (1) When the module is assembled, it should be attached to the system firmly.
 - Do not warp or twist the module during assembly work.
- (2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
- (3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
- (4) Do not allow drops of water or chemicals to remain on the display surface.

If you have the droplets for a long time, staining and discoloration may occur.

- (5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
- (6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.

Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.

- (7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
- (8) Protect the module from static; it may cause damage to the CMOS ICs.
- (9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
- (10) Do not disassemble the module.
- (11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
- (12) Pins of I/F connector shall not be touched directly with bare hands.
- (13) Do not connect, disconnect the module in the "Power ON" condition.
- (14) Power supply should always be turned on/off by the item 6.1 Power On Sequence &6.2 Power Off Sequence

9.2 Storage and Transportation.

- (1) Do not leave the panel in high temperature, and high humidity for a long time.
 It is highly recommended to store the module with temperature from 0°C to 35°C and relative humidity of less than 70%
- (2) Do not store the TFT-LCD module in direct sunlight.
- (3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
- (4) It is recommended that the modules should be stored under a condition where no condensation is allowed.Formation of dewdrops may cause an abnormal operation or a failure of the module.In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
- (5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.